PEELING TAPE ADHERING METHOD AND PEELING TAPE ADHERING DEVICE

ABSTRACT OF THE DISCLOSURE

A peeling tap adhering method for adhering a peeling tape (4) to a surface protection film (11) adhered to the front surface of a wafer (20), comprises the steps of: supporting the wafer on a table (31) under the condition that the surface protection film is directed upward; adhering the peeling tape onto the surface protection film by pressing the peeling tape onto the surface protection film when a peeling tape adhering means (46) is lowered; detecting the pressure between the surface protection film of the wafer and the peeling tape adhering means; and stopping the peeling tape adhering means from lowering in the case where a pressure detection value (P) is not less than a predetermined value (P0). Due to the foregoing, it is possible to prevent the wafer from being cracked. Further, it is possible to prevent the peeling tape and the dicing tape from adhering to each other. When the distance (L) between the surface protection film of the wafer and the peeling tape adhering means becomes a value not more than a predetermined value (L0), the peeling tape sticking means may be stopped from lowering.

FIGURE 1